# 微孔陶瓷工作盘
# Chuck tables for wafer processing

微孔陶瓷工作盘是各种半导体片生产过程中用于吸附及承载的专用工具。应用于减薄、划片、清洗、搬运等工序。我所生产的工作盘可以和日本、德国、以色列、美国及国产的设备配套使用，具有优越的性能价格比。

Fine-pore ceramic chuck tables are mainly used to support and chuck the semiconductor wafer when grinding and dicing. It is applied in the processes of thinning, dicing, clearance, transportation and so on. These products which have high cost performance produced by our institute can match with the machines made in Japan, Germany, Israel, America and China.

- **加工对象：** 2、3、4、5、6、8、12英寸半导体片
- **配套机床：** 减薄机、划片机、清洗机等
- **吸盘类型：** 微孔陶瓷

- **Workpiece processed:** 2,3,4,5,6,8,12 inches semiconductor wafer
- **Suitable devices:** Wafer grinder, dicing machine and cleaning machine ,etc
- **Chuck type:** Fine-pore ceramic

- **主要特点：**
  平面度、平行度高
  组织致密均匀，强度高
  通透性好，吸附力均匀
  易于修整

- **Characteristics:**
  High flatness and parallelism
  Compact and uniform microstructure with high strength
  Good permeability and uniform adsorption affinity
  Dressing easily

# 陶瓷载盘、修整环
# Ceramic plates and ring for polishing

我所可根据客户的需要制作外径、厚度不等的晶片CMP抛光用陶瓷载盘，该工作盘可用于3、4、5、6英寸晶片的CMP抛光使用，其平面度、平行度高，组织致密均匀，部分产品已经达到进口产品水平，具有优越的性价比。

还可根据用户的需要制作陶瓷修整环、陶瓷研磨盘等配件。

We could supply customers ceramic plates for CMP polishing with various outer diameter and thickness. This kind of table could be used for CMP polishing of 3, 4, 5, 6 inch wafer. It has advantages such as high flatness and parallelism, compact and uniform microstructure and high cost performance. Some of them could achieve superior imported product level.

Spare parts of Ceramic plates and ring for polishing can be made according to customers' requirement.